



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-09-05
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
DVIULC6-4SC6	CDWB*5XWSOIS	A	ZS1A	2013-09-05
Amount		UoM	Unit type	ST ECOPACK Grade
14.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	2.9 - 1.625 - 1.175	6	gull wing	
Comment	Package: SOT 23 - 6L. MDF valid also for FG & CP: DVIULC6-4SC6R/C, ADVIULC6-4SC6R/C (CP: DVIULC6-4SC6); AHDMIULC64SC6C/C, HDMIULC6-4SC6C/C (CP: HDMIULC6-4SC6)			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-19 Dec 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	CDWB*5XWSOIS					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	0.176	mg	supplier	die	Silicon (Si)	7440-21-3		0.171	mg	971591	12214
Silicon Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.002	mg	11364	143
Silicon Die				supplier	metallization	Copper (Cu)	7440-50-8		0.001	mg	5682	71
Silicon Die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.002	mg	11364	143
Lead-frame	Other inorganic materials	6.765	mg	supplier	alloy	Copper (Cu)	7440-50-8		6.518	mg	963489	465571
Lead-frame				supplier	alloy	Iron (Fe)	7439-89-6		0.154	mg	22764	11000
Lead-frame				supplier	alloy	Phosphorus (P)	12185-10-3		0.002	mg	296	143
Lead-frame				supplier	alloy	Zinc (Zn)	7440-66-6		0.008	mg	1183	571
Lead-frame				supplier	metallization	Nickel (Ni)	7440-02-0		0.076	mg	11234	5429
Lead-frame				supplier	metallization	Palladium (Pd)	7440-05-3		0.005	mg	739	357
Lead-frame				supplier	metallization	Gold (Au)	7440-57-5		0.002	mg	296	143
Die Attach	Other inorganic materials	0.069	mg	supplier	glue	Epoxyde Bisphenol A Resin	25068-38-6		0.019	mg	275362	1357
Die Attach				supplier	glue	Aromatic amine	Proprietary		0.003	mg	43478	214
Die Attach				supplier	glue	Glycol ether ester	Proprietary		0.003	mg	43478	214
Die Attach				supplier	glue	silica	60676-86-0		0.021	mg	304348	1500
Die Attach				supplier	glue	Aluminium oxide	1344-28-1		0.023	mg	333333	1643
Bonding wire	Other inorganic materials	0.16	mg	supplier	wire	Copper (Cu)	7440-50-8		0.157	mg	981250	11214
Bonding wire				supplier	wire	Palladium (Pd)	7440-05-3		0.003	mg	18750	214
encapsulation	Other inorganic materials	6.83	mg	supplier	mold compound	Silica, vitreous	60676-86-0		5.826	mg	853044	416286
encapsulation				supplier	mold compound	phenolic resin	Proprietary		0.239	mg	34982	17071
encapsulation				supplier	mold compound	epoxy resin	Proprietary		0.273	mg	39959	19500
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.137	mg	20053	9786
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.014	mg	2049	1000
encapsulation				supplier	mold compound	Zinc hydroxide	20427-58-1		0.068	mg	9953	4857
encapsulation				supplier	mold compound	Magnesium hydroxide	1309-42-8		0.273	mg	39959	19500